

What is Claimed is:

1. A method of integrating an optical element in an optical system comprising:
forming a plurality of optical elements on a top surface of a substrate;
etching a separation well having etched edges in at least one of the top surface of
the substrate and a bottom surface of a substrate for each optical element;
completing separation through the separation well using a non-etching technique
to form singulated optical elements; and
aligning a singulated optical element with the optical system using an etched
edge.
2. The method of claim 1, wherein a separation well is formed on both the top and
bottom surfaces of the substrate.
3. The method of claim 1, further comprising, before said completing separation,
securing another substrate to the substrate.
4. The method of claim 1, further comprising, before said completing separation,
securing a corresponding plurality of dies to the substrate.
5. The method of claim 1, wherein said etching is performed before said forming.
6. The method of claim 1, wherein said completing separation includes breaking the
substrate along the separation wells.
7. The method of claim 1, wherein said completing separation includes dicing along
the separation wells.
8. The method of claim 7, wherein said dicing includes dicing through the separation
wells using a dicing blade narrower than the separation wells.

9. The method of claim 7, wherein said dicing includes dicing through the substrate on the surface opposite the separation wells using a dicing blade wider than the separation wells.
10. The method of claim 1, wherein said completing separating includes thinning the substrate.
11. A method of creating a plurality of optical elements comprising:
forming a plurality of optical elements on a top surface of a substrate;
etching a corresponding plurality of separation wells on the top surface;
thinning the substrate from a back surface of the substrate, the combination of the thinning and etching singulate the optical elements.
12. The method of claim 11, wherein during completion of the singulating, the optical elements are provided on a support structure.
13. The method of claim 11, wherein the etching occurs before the thinning.
14. The method of claim 13, wherein the etching and the forming are simultaneous.
15. The method of claim 11, wherein the etching occurs after the thinning.